

General Description

The MY150N03K is the high cell density trenched N-CH MOSFETs, which provide excellent $R_{DS(on)}$ and gate charge for most of the synchronous buck converter applications.

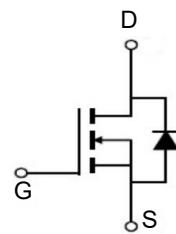
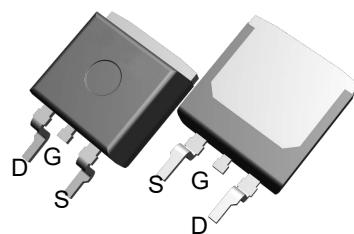


Features

V_{DSS}	30	V
I_D	150	A
$R_{DS(ON)}(\text{at } V_{GS}=10\text{V})$	1.6	$\text{m}\Omega$
$R_{DS(ON)}(\text{at } V_{GS}=4.5\text{V})$	3.2	$\text{m}\Omega$

Application

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY150N03K	TO-263	150N03	800

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		30	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	TC = 25°C	150	A
		TC = 100°C	110	A
I_{DM}	Pulsed Drain Current note1		310	A
EAS	Single Pulsed Avalanche Energy note2		246	mJ
P_D	Power Dissipation	TC = 25°C	80.3	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		1.4	°C/W
TJ, TSTG	Operating and Storage Temperature Range		-55 to +175	°C

Electrical Characteristics at $T_J=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.022	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=10\text{V}$, $I_D=30\text{A}$	---	1.6	3	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=15\text{A}$		3.2	4	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1	---	2.5	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	-6.1	---	$\text{mV}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	2	uA
		$V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	10	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{\text{DS}}=5\text{V}$, $I_D=30\text{A}$	---	60	---	S
R_g	Gate Resistance	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	0.9	---	
Q_g	Total Gate Charge (4.5V)	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=15\text{A}$	---	56.9	---	nC
Q_{gs}	Gate-Source Charge		---	13.8	---	
Q_{gd}	Gate-Drain Charge		---	23.5	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3.3\text{ }\Omega$, $I_D=1\text{A}$	---	20.1	---	ns
T_r	Rise Time		---	6.3	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	124.6	---	
T_f	Fall Time		---	15.8	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	5935	---	pF
C_{oss}	Output Capacitance		---	725	---	
C_{rss}	Reverse Transfer Capacitance		---	538	---	
I_s	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Current	---	---	155	A
I_{SM}	Pulsed Source Current ^{2,5}		---	---	310	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=A$, $T_J=25^\circ\text{C}$	---	---	1.2	V

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2 .The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=70.2\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5 .The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation. 6.Package limitation current is 85A.

Typical Characteristics

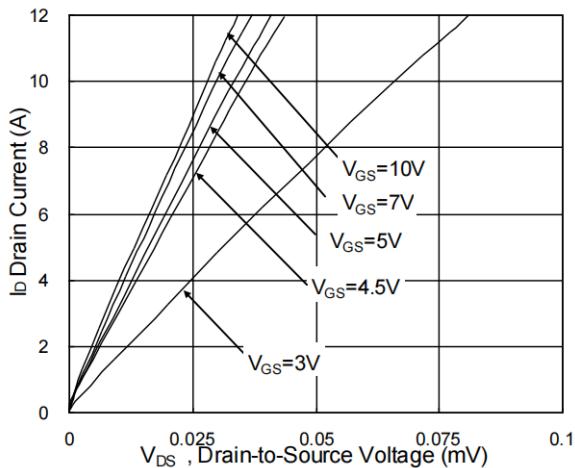


Fig.1 Typical Output Characteristics

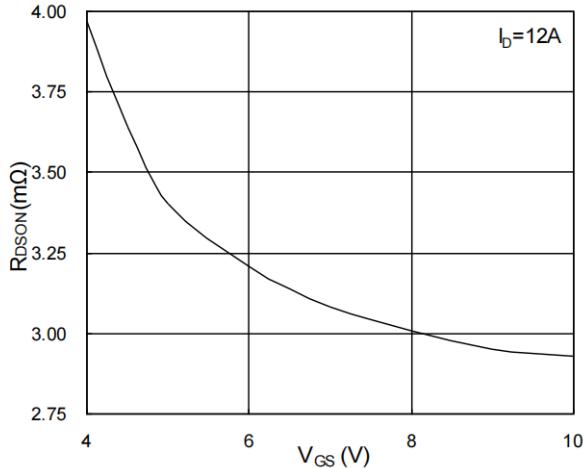


Fig.2 On-Resistance v.s Gate-Source

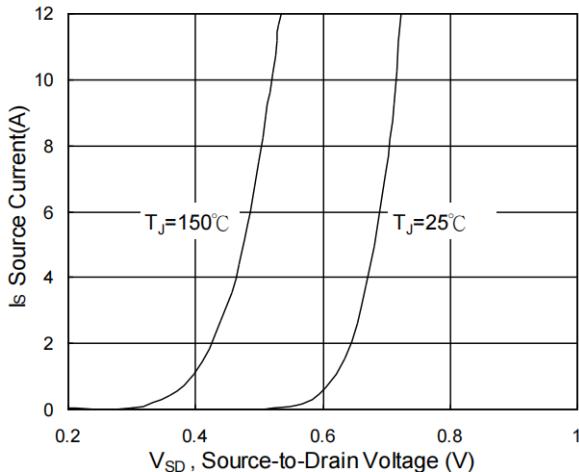


Fig.3 Forward Characteristics of Reverse

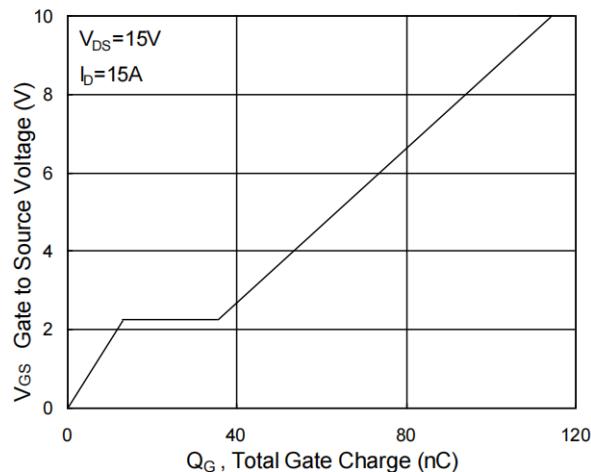
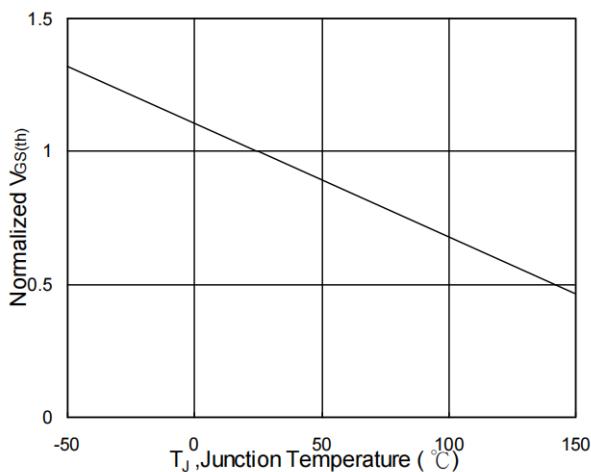
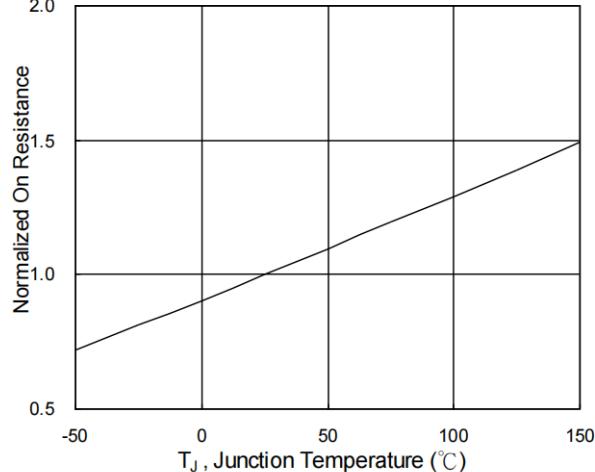


Fig.4 Gate-Charge Characteristics

Fig.5 Normalized $V_{GS(th)}$ v.s T_J Fig.6 Normalized $R_{DS(on)}$ v.s T_J

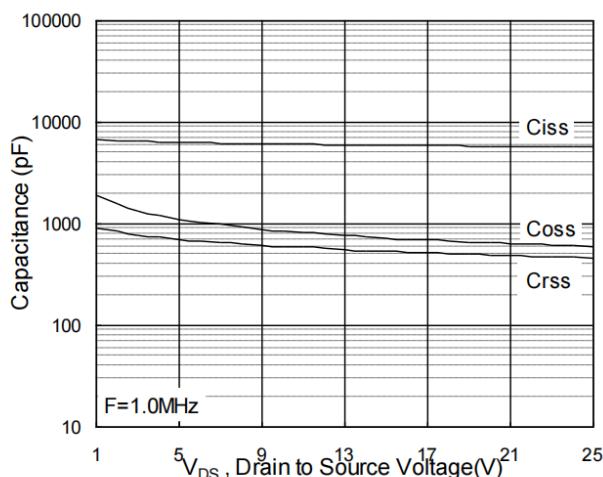


Fig.7 Capacitance

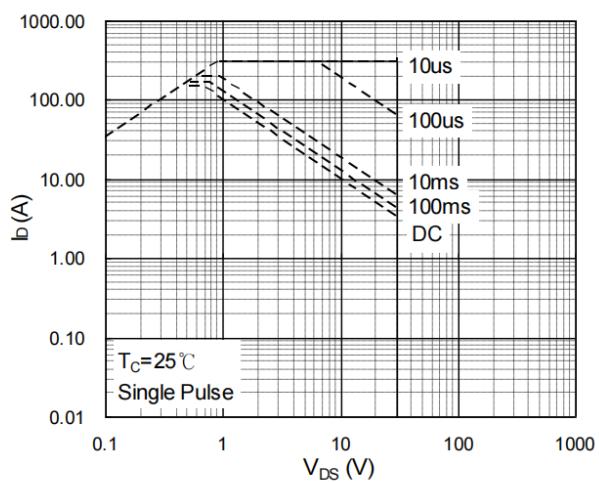


Fig.8 Safe Operating Area

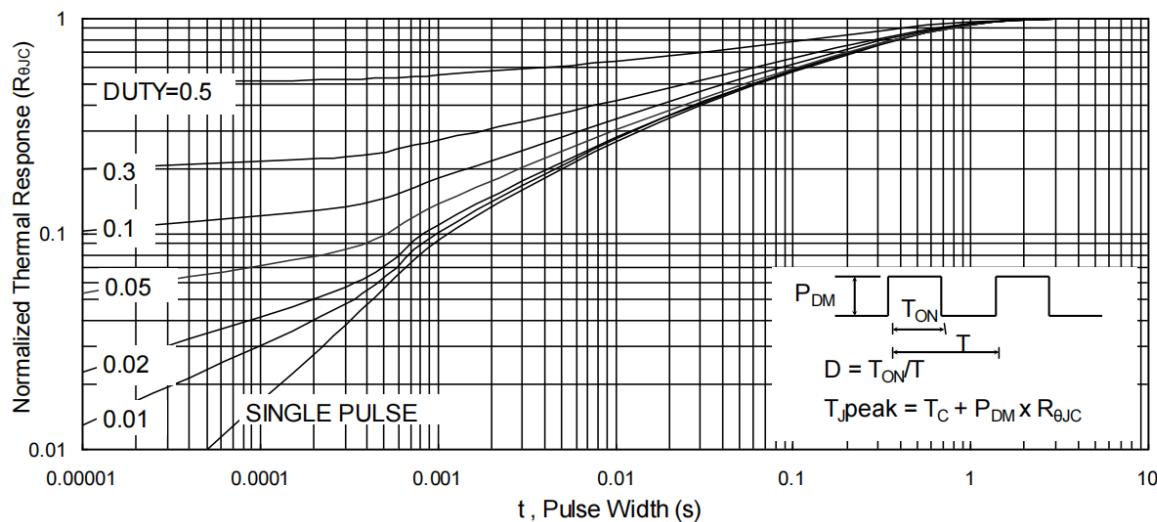


Fig.9 Normalized Maximum Transient Thermal Impedance

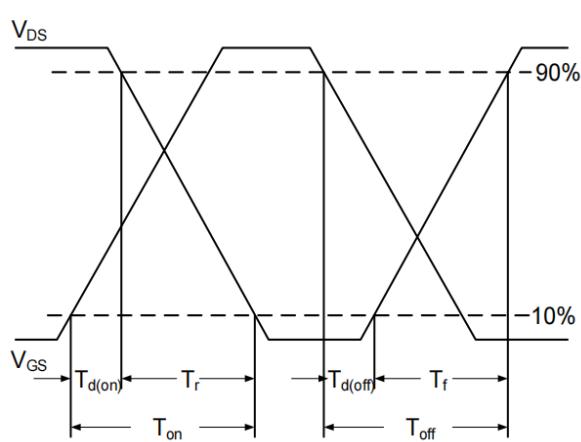


Fig.10 Switching Time Waveform

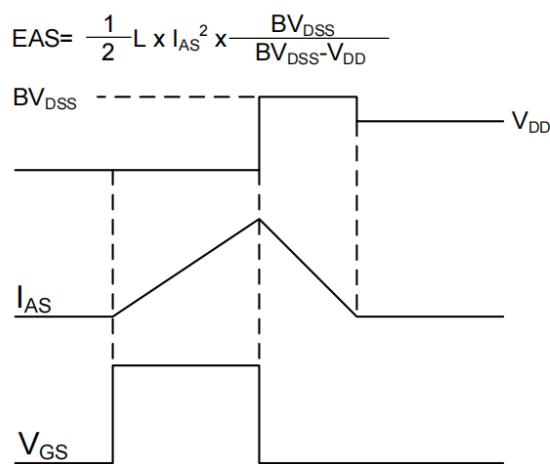
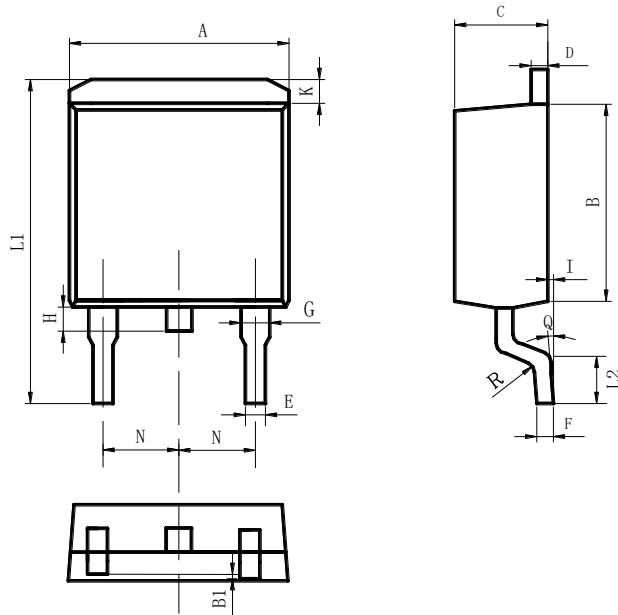


Fig.11 Unclamped Inductive Waveform

Package Mechanical Data-TO-263 Single


Items	Values(mm)	
	MIN	MAX
A	9.80	10.40
B	8.90	9.50
B1	0	0.10
C	4.40	4.80
D	1.16	1.37
E	0.70	0.95
F	0.30	0.60
G	1.07	1.47
H	1.30	1.80
K	0.95	1.37
L1	14.50	16.50
L2	1.90	2.90
I	0	0.2
Q	0°	8°
R	0.4	
N	2.39	2.69